

XMC3000 LID = P-00003-1-2 is 3 = 21 OCTOBER 2013
LAYER =

TOP COPPER LAYER

TOP SKIPPED LAYER

PCB Manufacturing Notes

General Info

Board dimensions – 130mm x 90mm
Number of layers – 4
Smallest hole – 0.3mm
Number of holes – Approx 630
Minimum Track & Gap – 0.125mm
RoHS/Lead Free – Yes
Material – FR4

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
Layer 01 (Top)	0.5oz
Layer 02 (Gnd)	1.0oz
Layer 03 (Power)	1.0oz
Layer 04 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

None required

Copper Thieving/Balancing

The supplier may add copper thieving/balancing if required.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

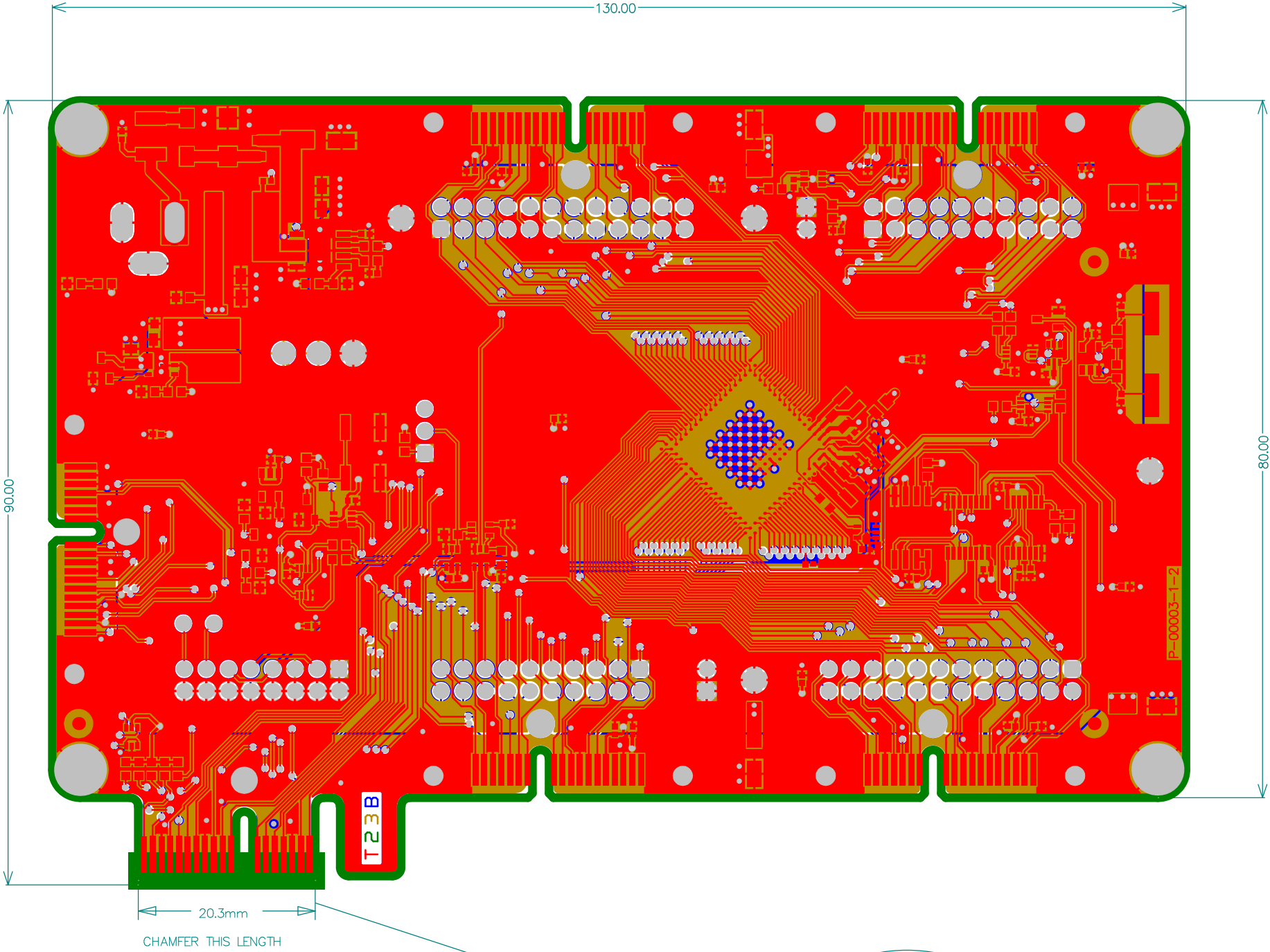
C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

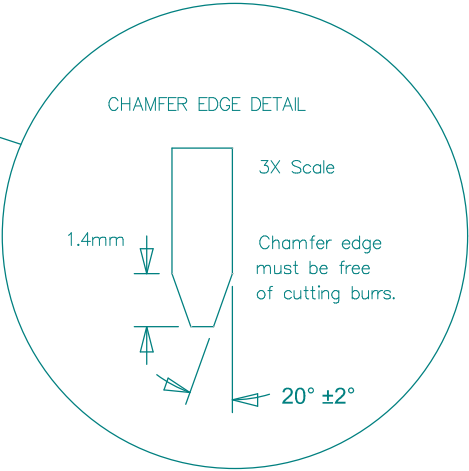
Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.

Hole size is finished size.



XMOS LTD = P-00003-1-2 iss 3 = 21 OCTOBER 2013
LAYER –
FABRICATION INSTRUCTIONS
TOP COPPER LAYER
BOTTOM COPPER LAYER
INNER 1 COPPER LAYER
INNER 2 COPPER LAYER

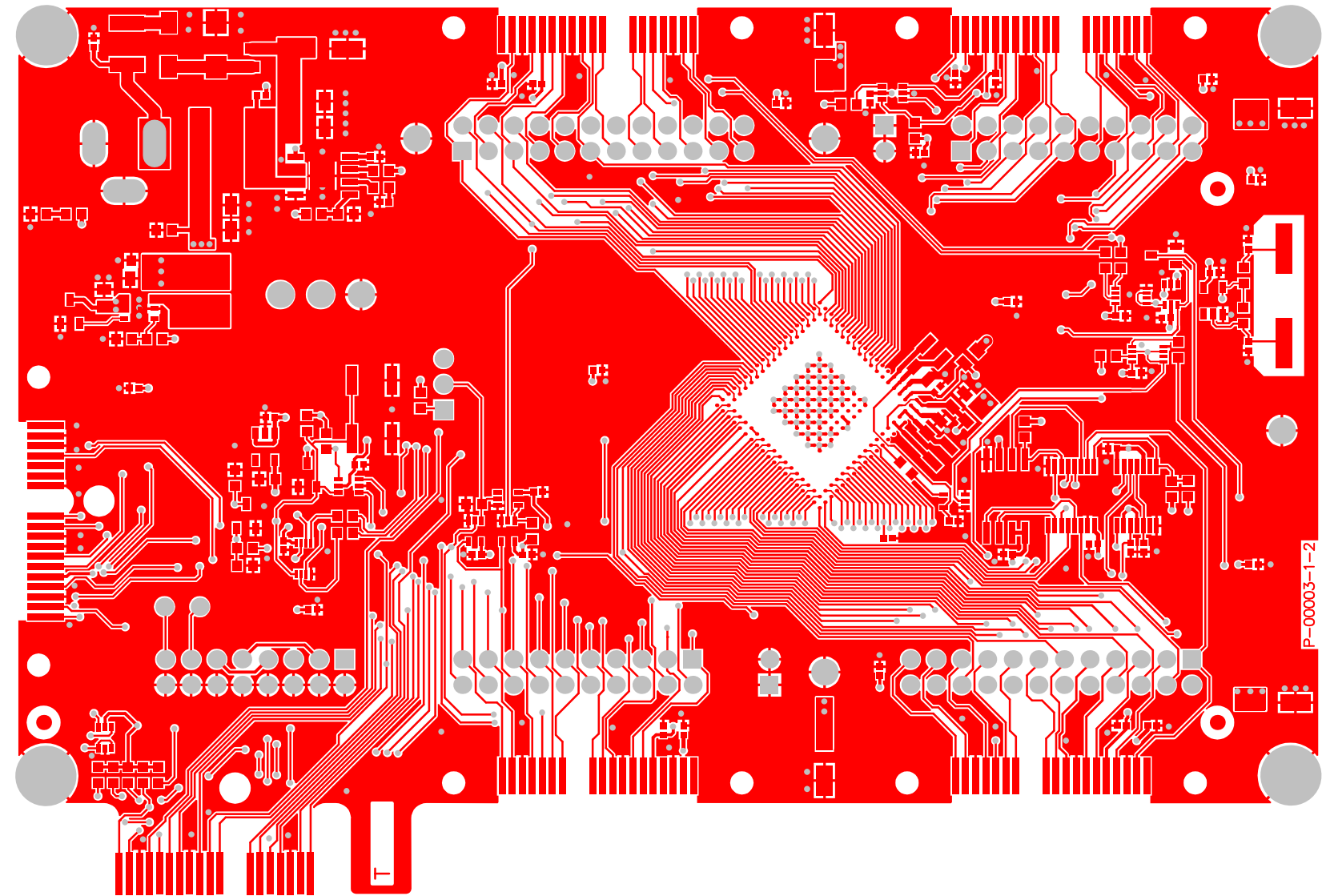


Project Name
P-00003-1-2 SLICEKIT CORE A16

Sheet	Date	Issue
A4	OCTOBER 2013	3

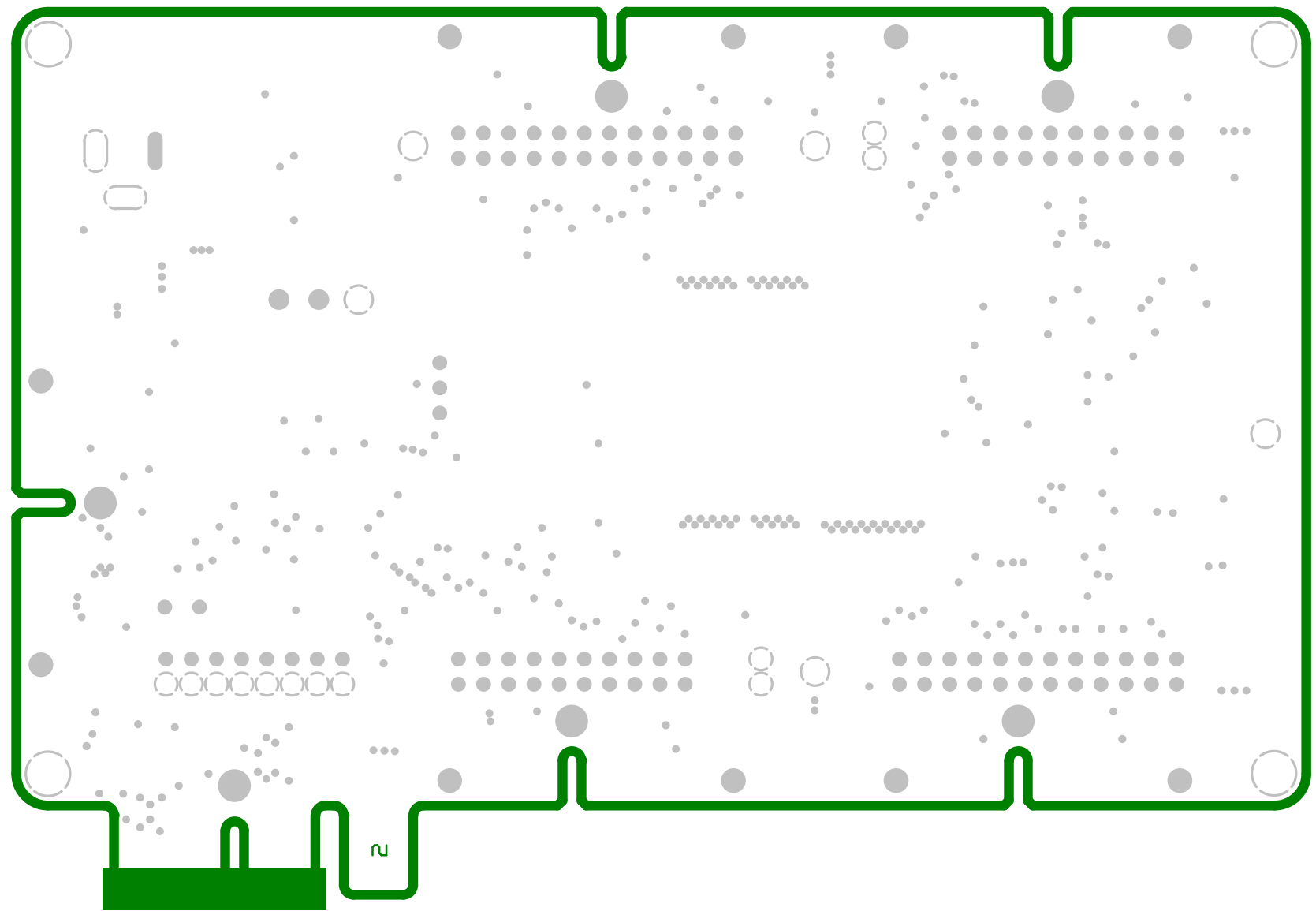
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Layer 01 (Top)



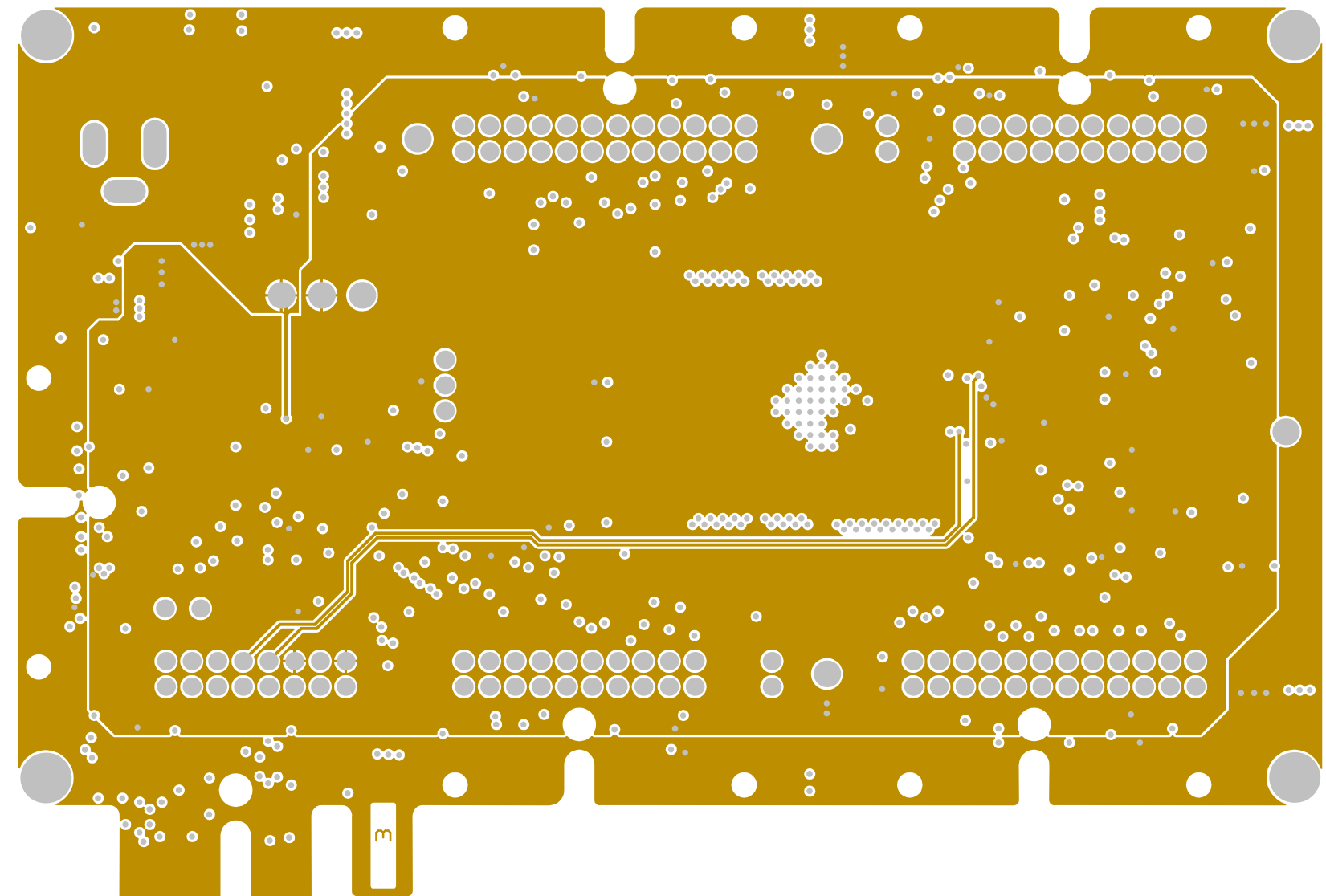
TOP COPPER LAYER

Layer 02 (Gnd)



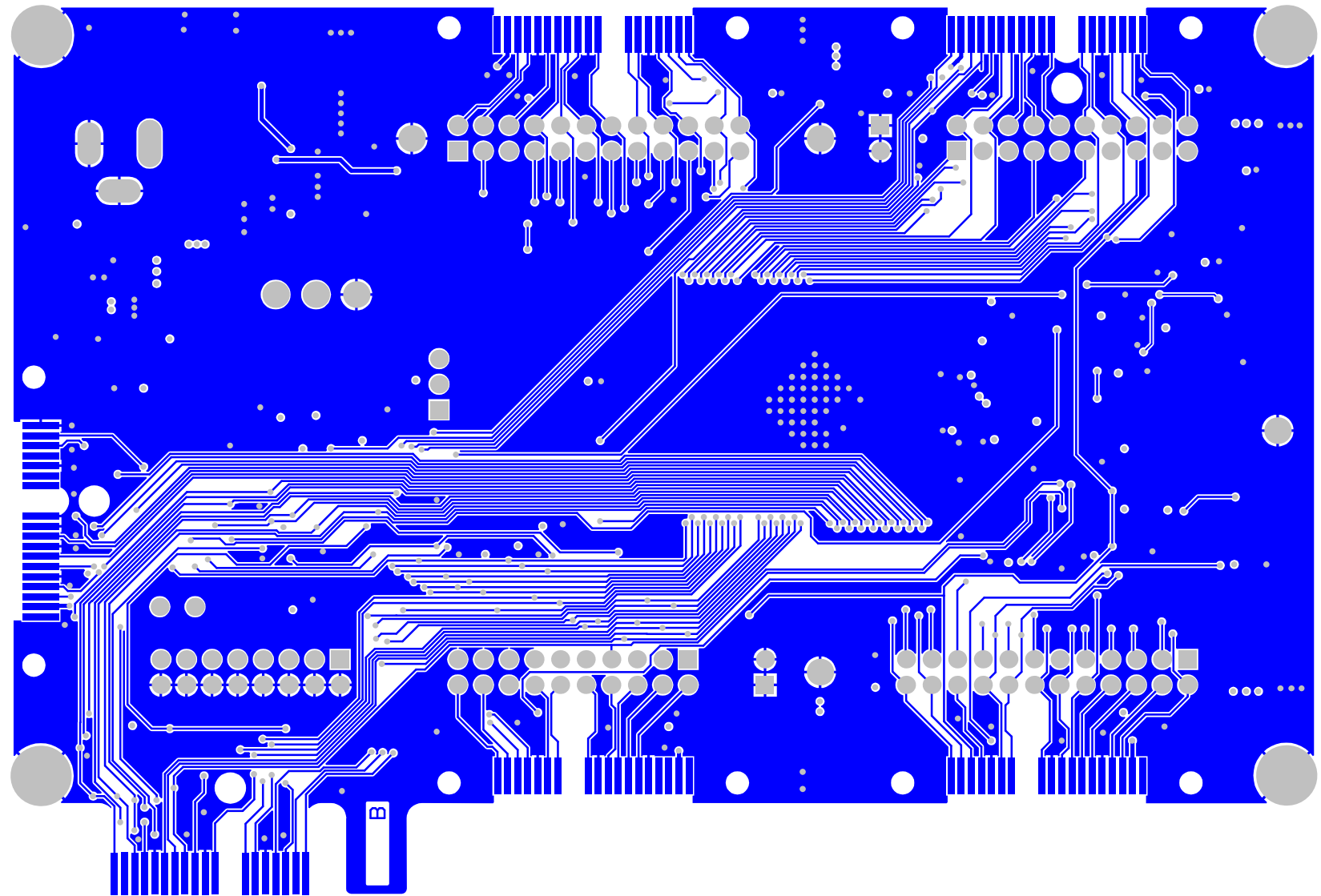
INNER 1 COPPER LAYER

Layer 03 (Power)



INNER 2 COPPER LAYER

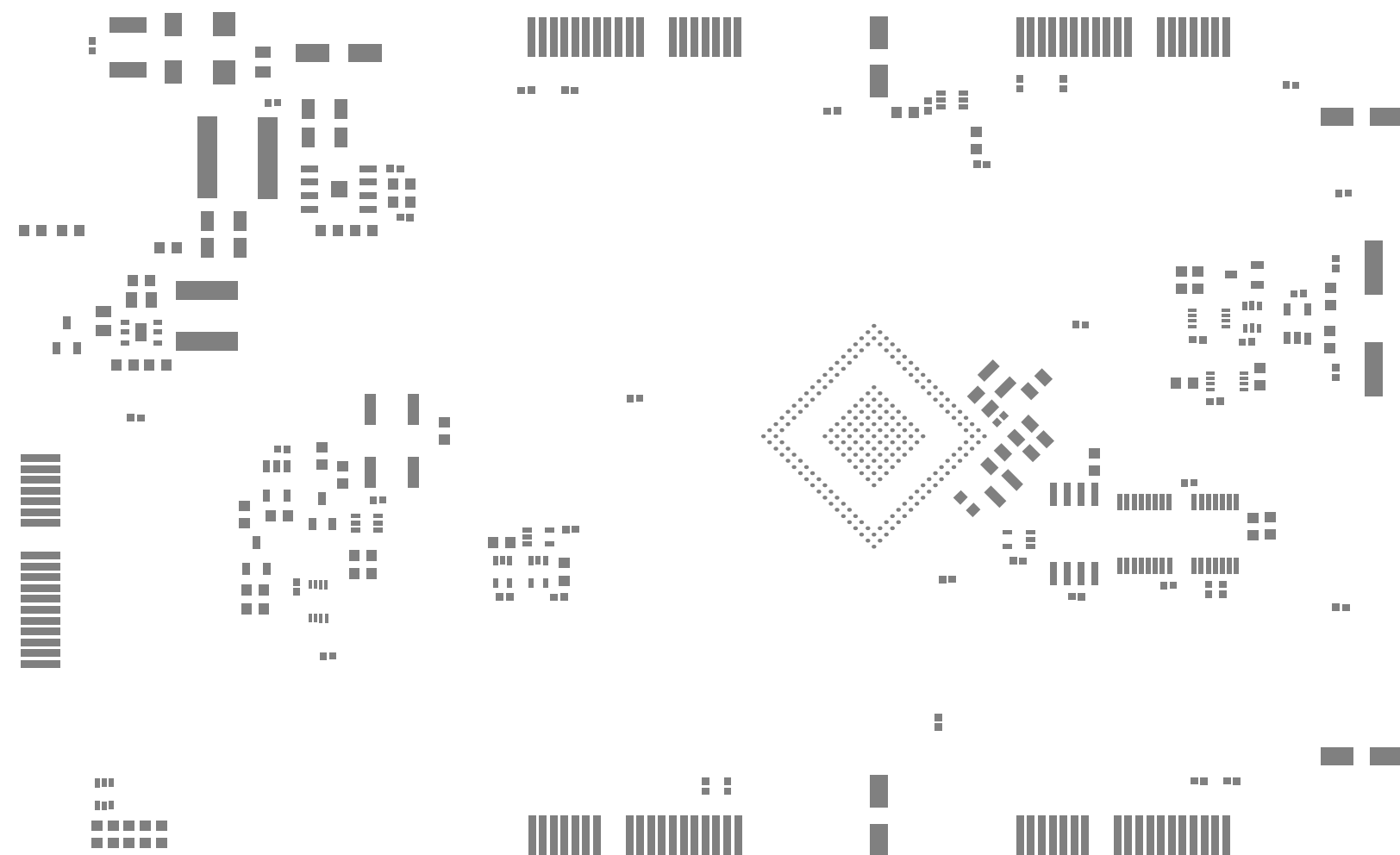
Layer 04 (Bottom)



BOTTOM COPPER LAYER



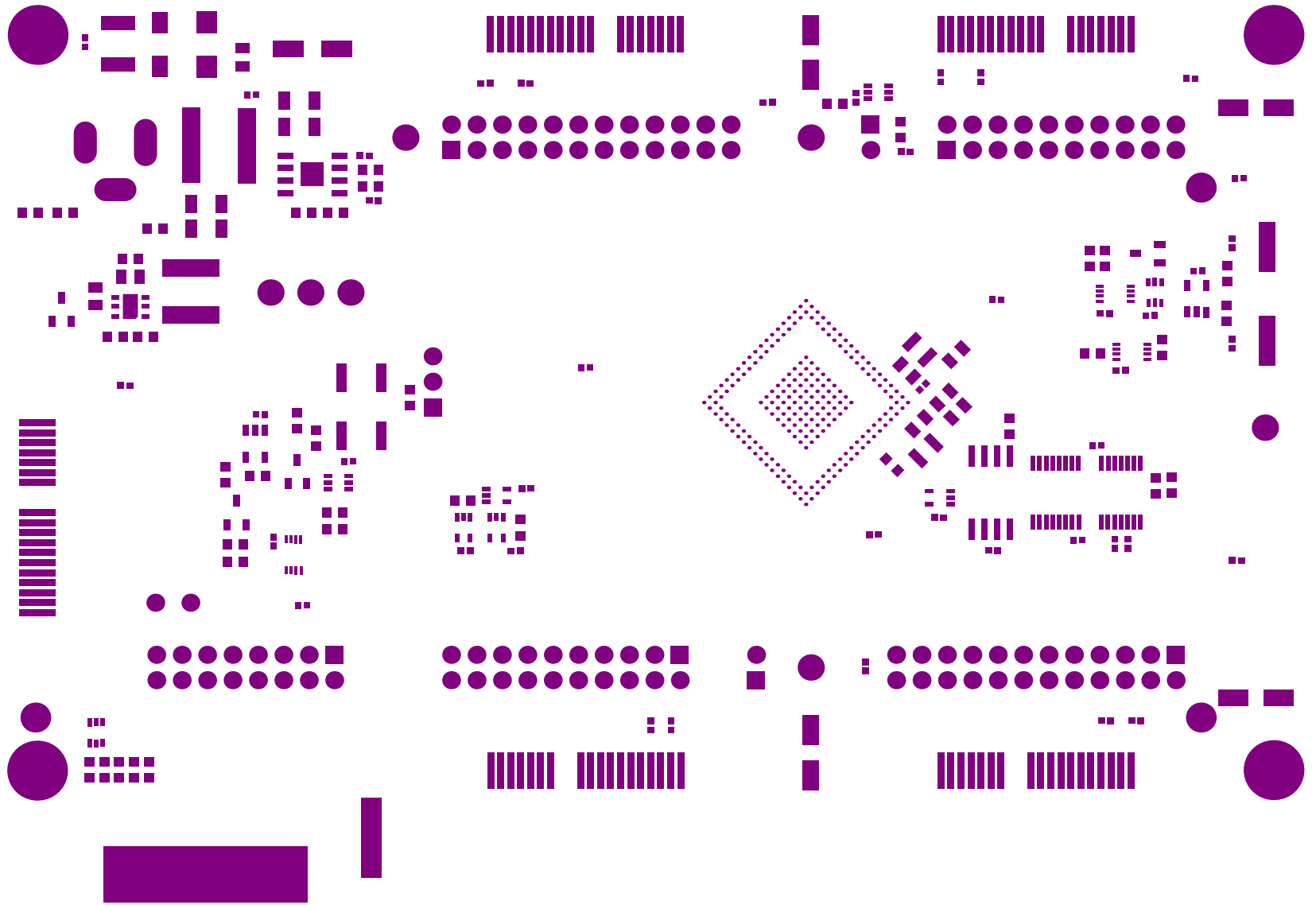
BOTTOM SILKSCREEN LAYER



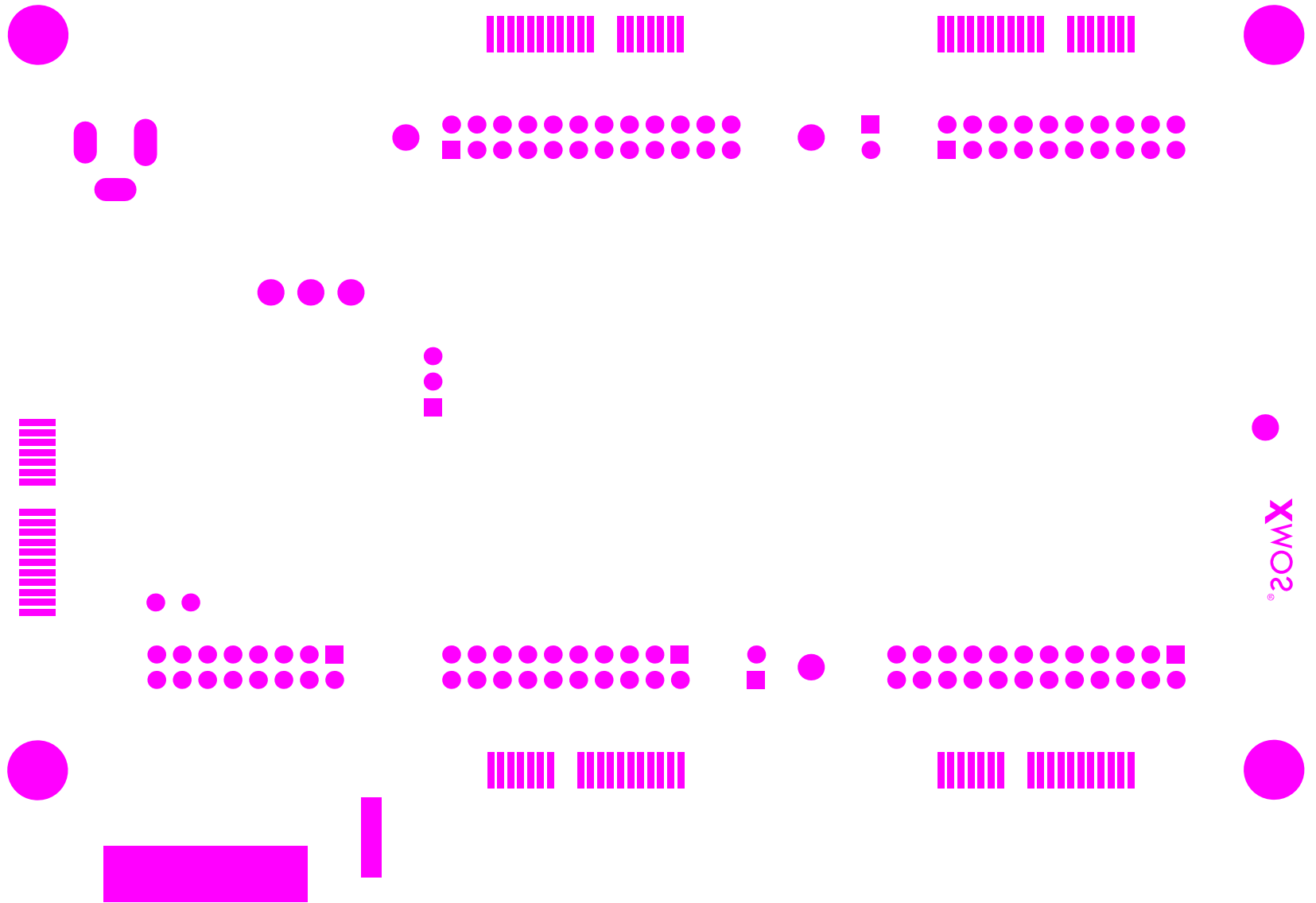
TOP PASTE LAYER



BOTTOM PASTE LAYER



TOP SOLDER MASK LAYER



XW02®

BOTTOM SOLDER MASK LAYER

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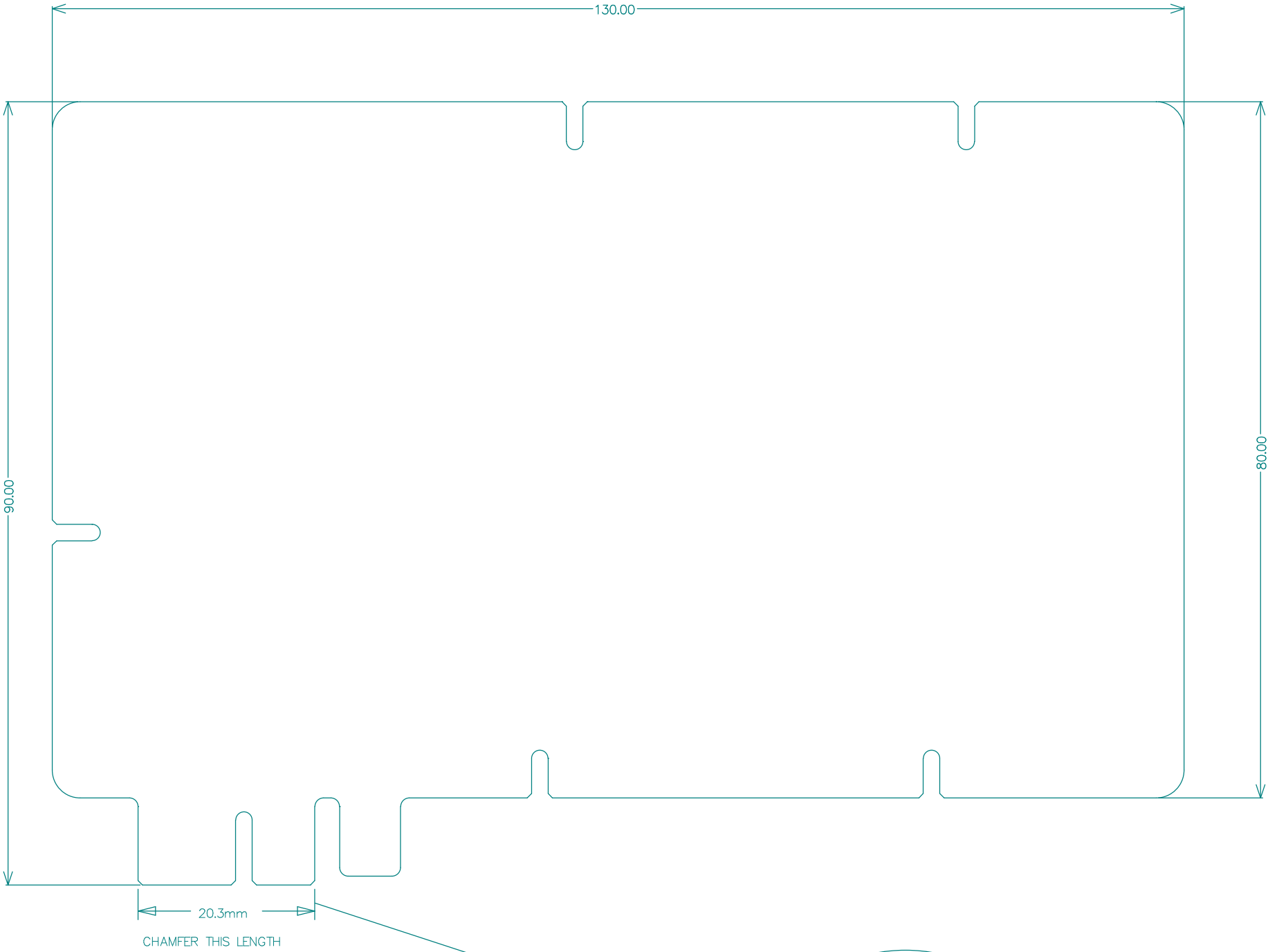
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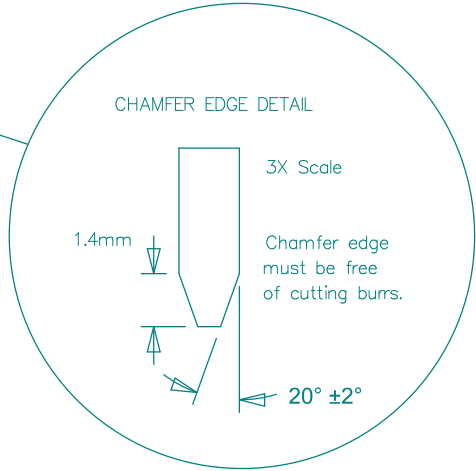
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FABRICATION INSTRUCTIONS



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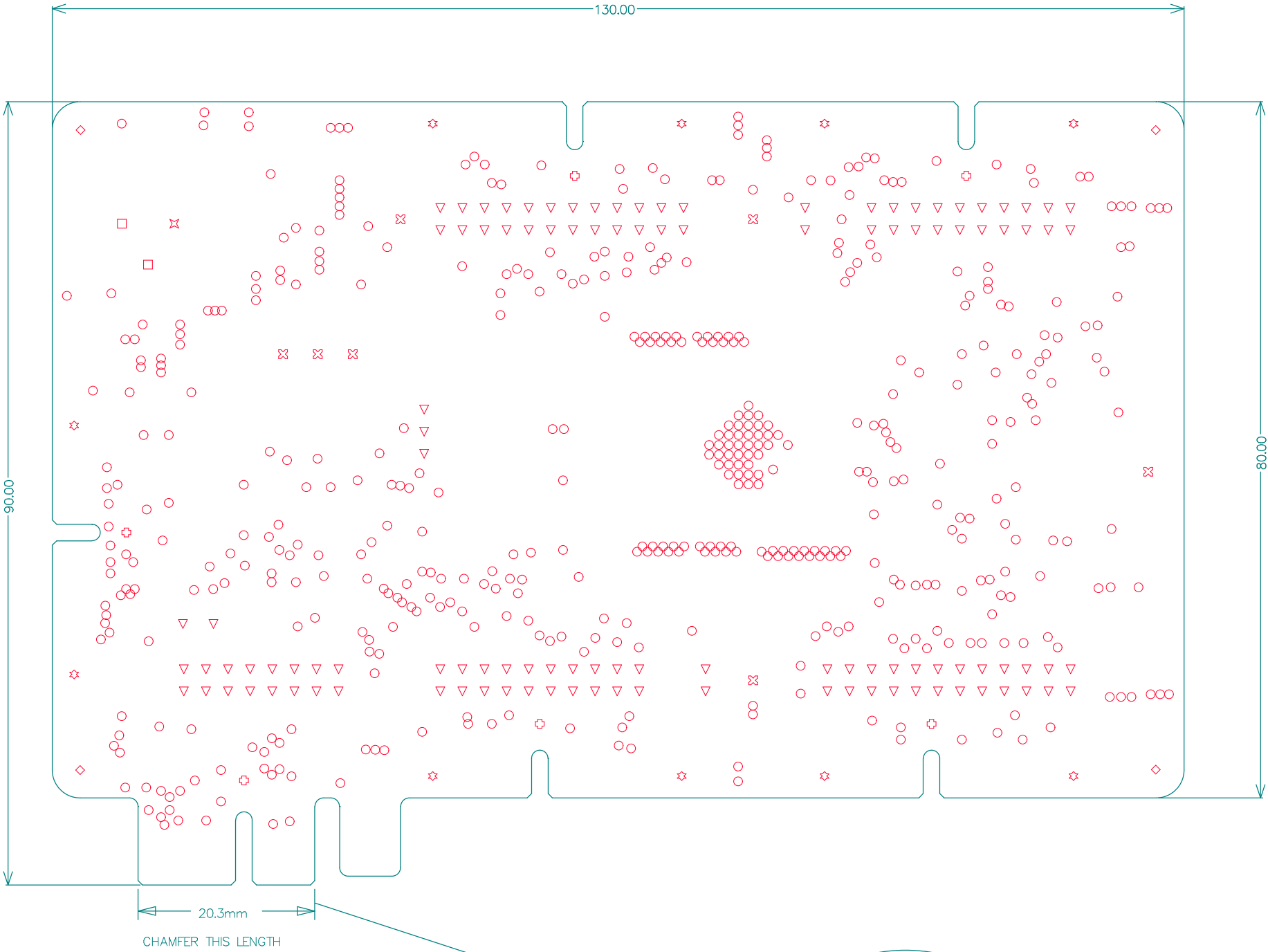
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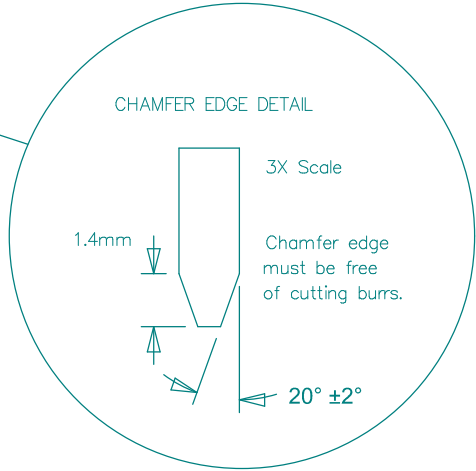


FABRICATION INSTRUCTIONS DRILL DRAWING

Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
○	488	0.3mm <11.811mil>			PTH	Round
▽	113	1mm <39.37mil>			PTH	Round
⊗	7	1.6mm <62.992mil>			PTH	Round
☆	10	2mm <78.74mil>			NPTH	Round
⊕	6	2.8mm <110.236mil>			NPTH	Round
◇	4	3.2mm <125.984mil>			PTH	Round
□	2	1mm <39.37mil>	2.9mm <114.173mil>	1.9mm <74.803mil>	PTH	Slot
⊠	1	1mm <39.37mil>	3.4mm <133.858mil>	2.4mm <94.488mil>	PTH	Slot
	631 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Drawing



Project Name

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Sheet

A4

Date

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Issue

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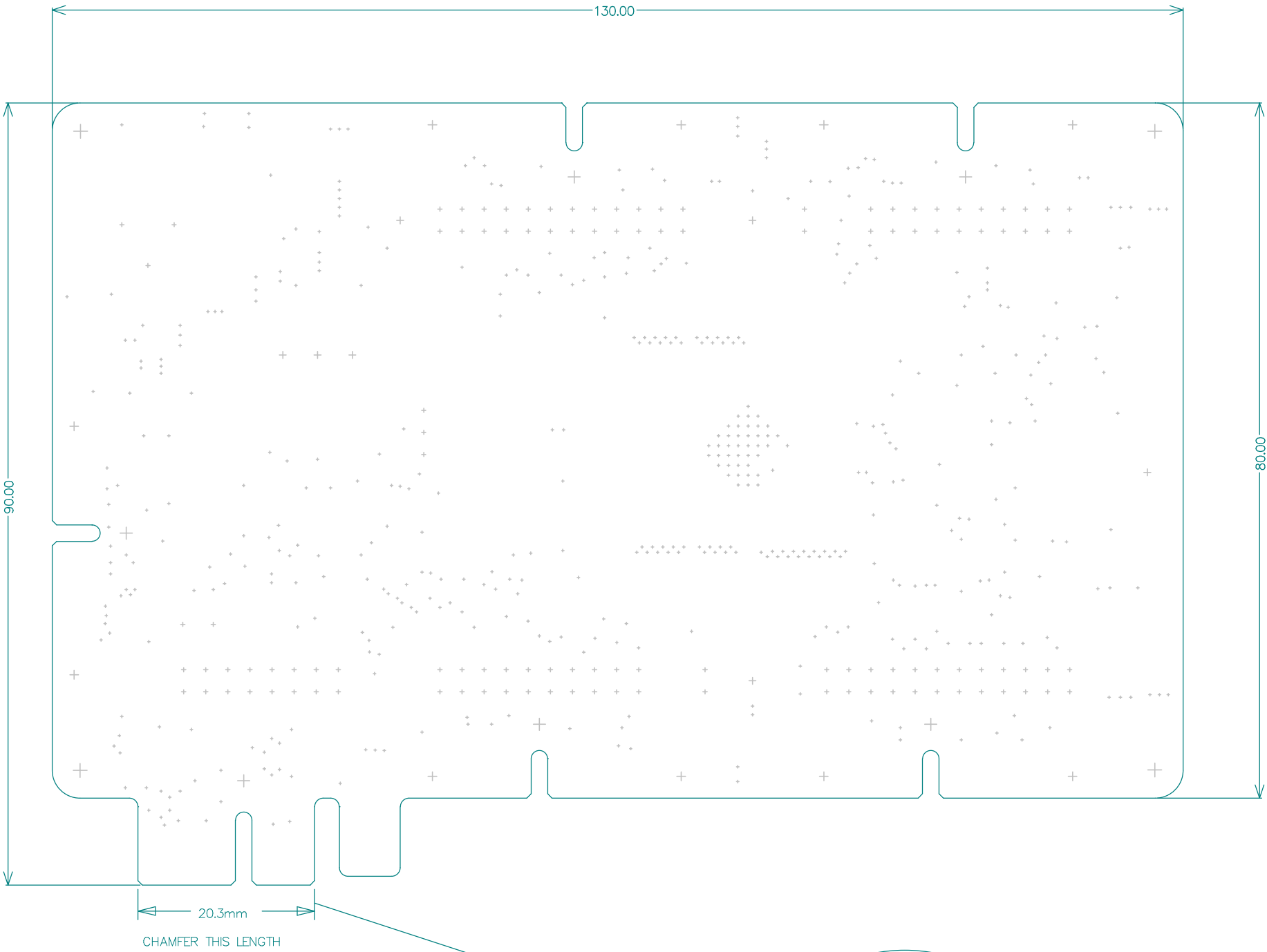
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FABRICATION INSTRUCTIONS

DRILL GUIDE

